

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Siamak Fazelpour

Serial No.: 10/025,438

Filed: December 19, 2001

For: Method For Integrating Passives
On-Die Utilizing Under Bump Metal

And Related Structure

Art Unit: 2812

Examiner: Nguyen, Ha T.

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FEB 13 2003
TECHNOLOGY CENTER 2800

AMENDMENT AND RESPONSE TO OFFICE ACTION

Honorable Commissioner of Patents and Trademarks Washington, D.C. 20231

Dear Sir/Madam:

This is in response to the Office Action dated October 4, 2002 in the abovereferenced patent application. Please enter and consider the following amendments and remarks.

02/12/2003 DTESSEM1 00000046 10025438

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